

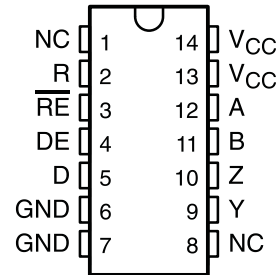
DIFFERENTIAL DRIVER AND RECEIVER PAIR

Check for Samples: [SN75ALS181](#)

FEATURES

- Meets TIA/EIA-422-B, TIA/EIA-485-A, and CCITT Recommendations V.11 and X.27
- Low Supply-Current Requirements...
30 mA Max
- Driver Output Capacity...±60 mA
- Thermal Shutdown Protection
- Driver Common-Mode Output Voltage Range of –7 V to 12 V
- Receiver Input Impedance...12 kΩ Min
- Receiver Input Sensitivity...±200 mV
- Receiver Input Hysteresis...60 mV Typ
- Receiver Common-Mode Input Voltage Range of ±12 V
- Operates From Single 5-V Supply
- Glitch-Free Power-Up and Power-Down Protection

N OR NS PACKAGE
(TOP VIEW)



N.C. – No internal connection

DESCRIPTION

The SN75ALS181 is a differential driver and receiver pair designed for bidirectional data communication on multipoint bus transmission lines. The design provides for balanced transmission lines and meets TIA/EIA-422-B and TIA/EIA-485-A, and CCITT recommendations V.10, V.11, X.26, and X.27.

The SN75ALS181 combines a 3-state differential line driver and a differential-input line receiver that operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be connected together externally to function as a direction control. The driver differential outputs and the receiver differential inputs are connected to separate pins for greater flexibility and are designed to offer minimum loading to the bus when the driver is disabled or $V_{CC} = 0$. These ports feature wide positive and negative common-mode voltage changes, making the device suitable for party-line applications.

ORDERING INFORMATION

T _A	PACKAGE ^{(1) (2)}	ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tape and reel	SN75ALS181N
	SOP – NS	Tape and reel	SN75ALS181NSR
			75ALS181

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

FUNCTION TABLES

Each Driver

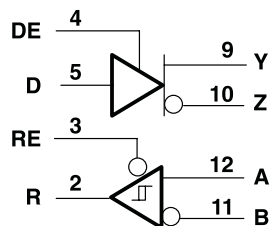
INPUTS D	ENABLE DE	OUTPUTS	
		Y	Z
H	H	H	L
L	H	L	H
X	L	Z	Z

Each Receiver⁽¹⁾

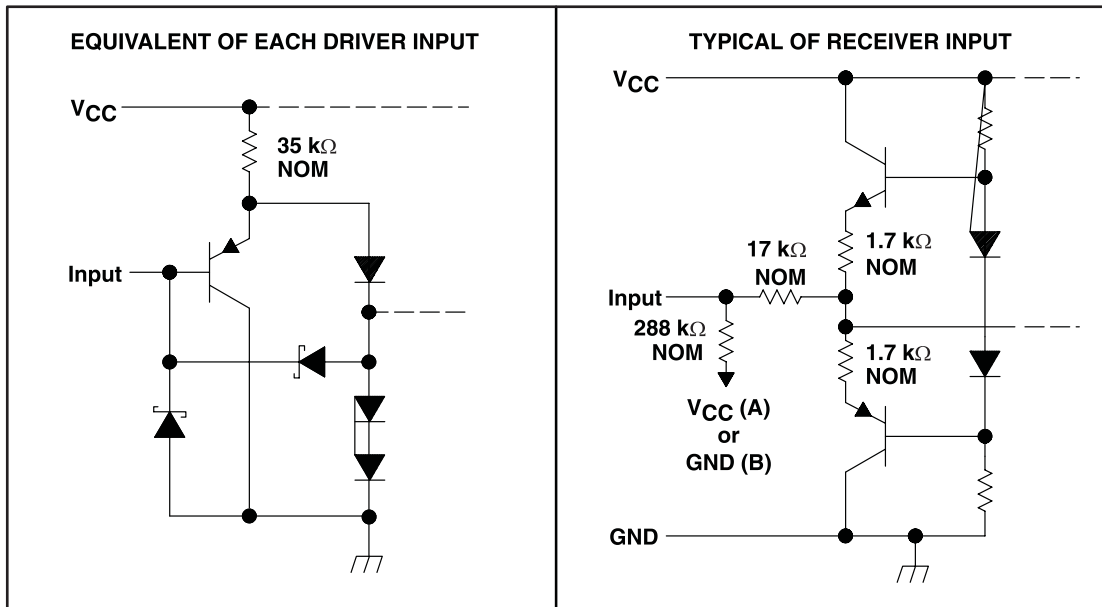
DIFFERENTIAL A–B	ENABLE RE	OUTPUT R
$V_{ID} \geq 0.2 \text{ V}$	L	H
$-0.2 \text{ V} < V_{ID} < 0.2 \text{ V}$	L	?
$V_{ID} \leq -0.2 \text{ V}$	L	L
X	H	Z

- (1) H = high level, L = low level, ? = indeterminate, X = irrelevant,
Z = high impedance (off)

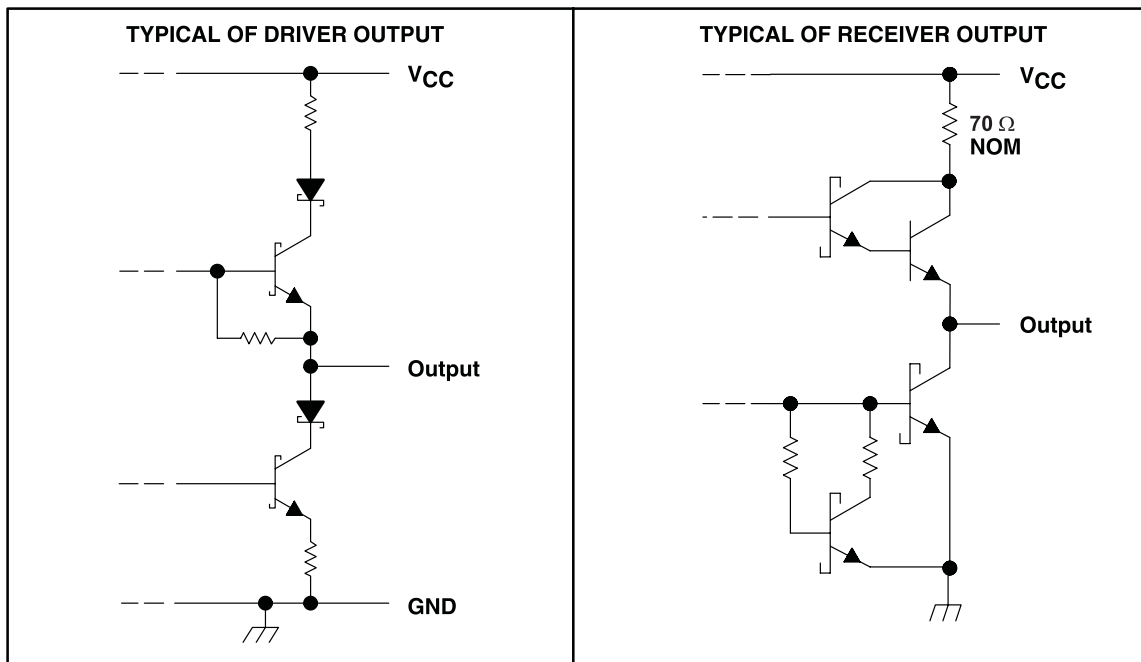
LOGIC DIAGRAM (POSITIVE LOGIC)



SCHEMATICS OF INPUTS



SCHEMATICS OF OUTPUTS



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT		
V _{CC}	Supply voltage range ⁽²⁾		7	V		
	Input voltage range	D, DE, and \overline{RE} inputs		7	V	
	Output voltage range	Driver		-9	14	V
	Input voltage range	Receiver		-14	14	V
	Receiver differential input voltage range ⁽³⁾			-14	14	V
θ_{JA}	Package thermal impedance ⁽⁴⁾⁽⁵⁾	N package		80	°C/W	
		NS package		76		
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds			260	°C		
T _{stg}	Storage temperature range	-65	150	°C		

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential input voltage, are with respect to network ground terminal.
- (3) Differential input voltage is measured at the noninverting terminal with respect to the inverting terminal.
- (4) Maximum power dissipation is a function of T_{J(max)}, θ_{JA} , and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $PD = (T_{J(max)} - T_A) / \theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (5) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT	
V _{CC}	Supply voltage	4.75	5	5.25	V	
V _{OC}	Common-mode output voltage ⁽¹⁾	Driver		-7	12	V
V _{IC}	Common-mode input voltage ⁽¹⁾	Receiver		-12	12	V
V _{IH}	High-level input voltage	D, DE, and \overline{RE}		2		V
V _{IL}	Low-level input voltage	D, DE, and \overline{RE}			0.8	V
V _{ID}	Differential input voltage			±12		V
I _{OH}	High-level output current	Driver			-60	mA
		Receiver			-400	µA
I _{OL}	Low-level output current	Driver			60	mA
		Receiver			8	
T _A	Operating free-air temperature	0		70	°C	

- (1) The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this table for common-mode output voltage level only.

Driver Section

ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IK}	Input clamp voltage	I _I = -18 mA				-1.5	V
V _O	Output voltage	I _O = 0		0		6	V
V _{OD1}	Differential output voltage	I _O = 0		1.5		6	V
V _{OD2}	Differential output voltage	V _{CC} = 5 V, R _L = 100 Ω	See Figure 1	1/2 V _{OD1}		5	V
		R _L = 54 Ω		2	2.3		
V _{OD3}	Differential output voltage	V _{test} = -7 V to 12 V,	See Figure 2	1.5		5	V
Δ V _{OD}	Change in magnitude of differential output voltage	R _L = 54 Ω or 100 Ω,	See Figure 1			±0.5	V
V _{OC}	Common mode output voltage	R _L = 54 Ω or 100 Ω,	See Figure 1	3		-1	V
				-1			
Δ V _{OC}	Change in magnitude of common-mode output voltage ⁽²⁾	R _L = 54 Ω or 100 Ω,	See Figure 1			±0.2	μA
I _{OZ}	High-impedance-state output current	V _O = -7 V to 12 V ⁽³⁾				±100	μA
I _{IH}	High-level input current	V _{IH} = 2.4 V				20	μA
I _{IL}	Low-level input current	V _{IL} = 0.4 V				-100	μA
I _{OS}	Short circuit output current	V _O = -7 V				-250	mA
		V _O = V _{CC}				250	
		V _O = 12 V				250	
		V _O = 0 V				-150	
I _{CC}	Supply current (total package)	No load	Outputs enabled		21	30	mA
			Outputs disabled		14	21	

(1) All typical values are at V_{CC} = 5 V and TA = 25°C.

(2) Δ|V_{OD}| and Δ|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.

(3) This applies for both power on and power off. Refer to TIA/EIA-485-A for exact conditions

SWITCHING CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
t _{dD}	Differential output delay time, t _{dDH} or t _{dDL}	R _L = 54 Ω,	C _L = 50 pF, See Figure 3	9	13	20	ns
t _{sk(p)}	Pulse skew (t _{dDH} - t _{dDL})	R _L = 54 Ω,	C _L = 50 pF, See Figure 3		1	8	ns
t _t	Differential output transition time	R _L = 54 Ω,	C _L = 50 pF, See Figure 3	3	10	16	ns
t _{PZH}	Output enable time to high level	R _L = 110 Ω,	See Figure 4		36	53	ns
t _{PZL}	Output enable time to low level	R _L = 110 Ω,	See Figure 5		39	56	ns
t _{PHZ}	Output disable time from high level	R _L = 110 Ω,	See Figure 4		20	31	ns
t _{PLZ}	Output disable time from low level	R _L = 110 Ω,	See Figure 5		9	20	ns

(1) All typical values are at V_{CC} = 5 V and TA = 25°C.

Receiver Section

ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT	
V_{T+}	Positive-going threshold voltage, differential input	$V_O = 2.7\text{ V}$,	$I_O = -0.4\text{ mA}$			0.2	V	
V_{T-}	Negative-going threshold voltage, differential input	$V_O = 0.5\text{ V}$,	$I_O = 8\text{ mA}$	-0.2			V	
V_{hys}	Input hysteresis ($V_{T+} - V_{T-}$)				60		mV	
V_{IK}	Input clamp voltage, \overline{RE}	$I_I = -18\text{ mA}$				-1.5	V	
V_{OH}	High-level output voltage	$V_{ID} = 200\text{ mV}$,	$I_{OH} = -400\text{ }\mu\text{A}$, See Figure 6	2.7			V	
V_{OL}	Low-level output voltage	$V_{ID} = 200\text{ mV}$,	$I_{OL} = 8\text{ mA}$, See Figure 6			0.45	V	
I_{OZ}	High-impedance-state output current	$V_O = 0.4\text{ V to } 2.4\text{ V}$				± 20	μA	
I_I	Line input current	Other input at 0 V ⁽²⁾ ,	$V_I = 12\text{ V}$			1	mA	
			$V_I = -7\text{ V}$			-0.8		
I_{IH}	High-level input current, \overline{RE}	$V_{IH} = 2.7\text{ V}$				20	μA	
I_{IL}	Low-level input current, \overline{RE}	$V_{IL} = -7\text{ V}$				-100	μA	
R_I	Input resistance			12			k Ω	
I_{OS}	Short circuit output current	$V_{ID} = 200\text{ mV}$,	$V_O = 0\text{ V}$	-15		-85	mA	
I_{CC}	Supply current (total package)	No load	Outputs enabled			21	30	mA
			Outputs disabled			14	21	

(1) All typical values are at $V_{CC} = 5\text{ V}$ and $TA = 25^\circ\text{C}$.

(2) This applies for both power on and power off. Refer to TIA/EIA-485-A for exact conditions

SWITCHING CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
t_{PHL}	Differential output delay time, td_{DH} or td_{DL}	$V_{ID} = -1.5\text{ V to } 1.5\text{ V}$		10	16	25	ns
t_{PLH}	Propagation delay time, low- to high-level output	$V_{ID} = -1.5\text{ V to } 1.5\text{ V}$		10	16	25	ns
$t_{sk(p)}$	Pulse skew ($ td_{DH} - td_{DL} $)	$V_{ID} = -1.5\text{ V to } 1.5\text{ V}$			1	8	ns
t_{PZH}	Output enable time to high level				7	15	ns
t_{PZL}	Output enable time to low level				9	19	ns
t_{PHZ}	Output disable time from high level				18	27	ns
t_{PLZ}	Output disable time from low level				10	15	ns

(1) All typical values are at $V_{CC} = 5\text{ V}$ and $TA = 25^\circ\text{C}$.

PARAMETER MEASUREMENT INFORMATION

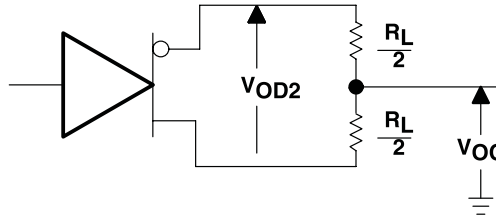


Figure 1. Driver Test Circuit, V_{OD} and V_{OC}

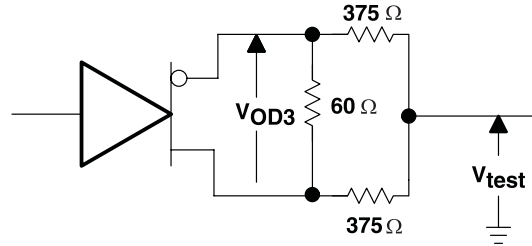


Figure 2. Driver Circuit, V_{OD3}

- A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1$ MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$
- B. C_L includes probe and jig capacitance.

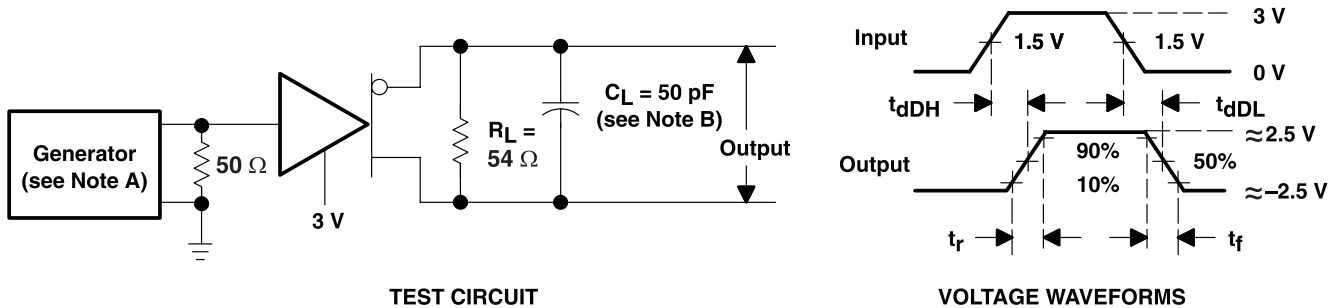


Figure 3. Driver Differential-Output Delay and Transition Times

- C. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1$ MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$
- D. C_L includes probe and jig capacitance.

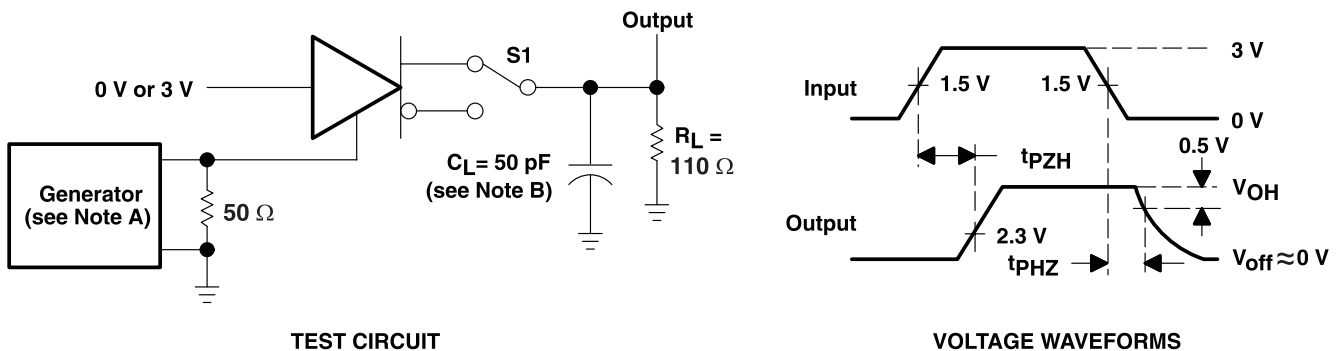


Figure 4. Driver Enable and Disable Times

- E. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1$ MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$
- F. C_L includes probe and jig capacitance.

PARAMETER MEASUREMENT INFORMATION (continued)

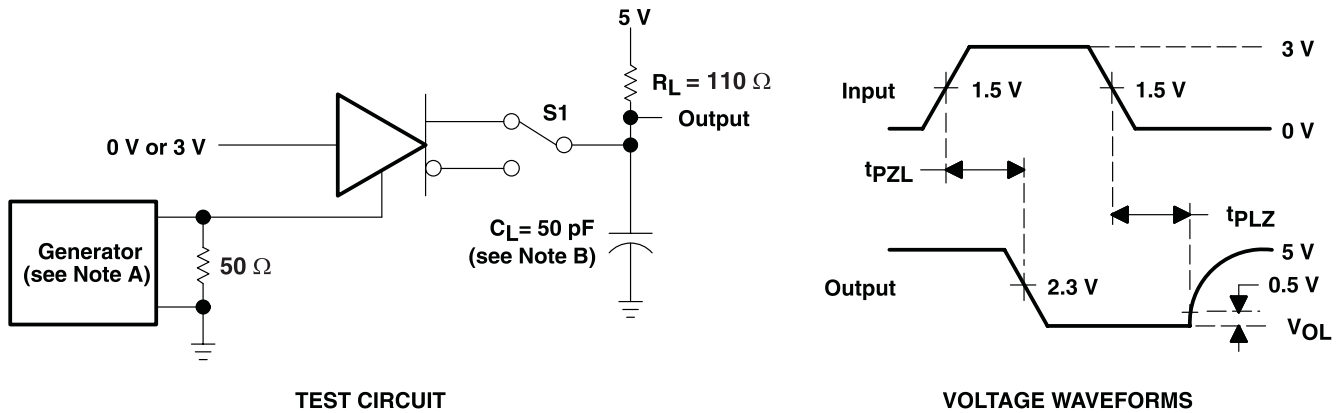


Figure 5. Driver Enable and Disable Times

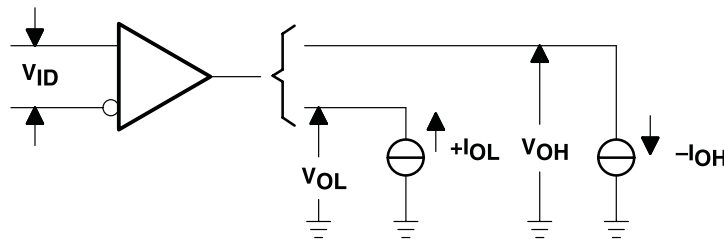


Figure 6. Receiver, V_{OH} and V_{OL}

- G. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1$ MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_o = 50 \Omega$
- H. C_L includes probe and jig capacitance.

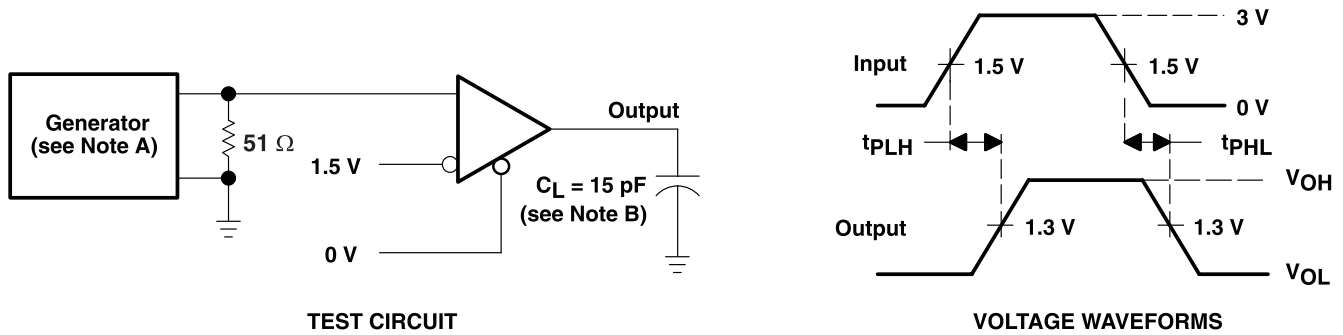
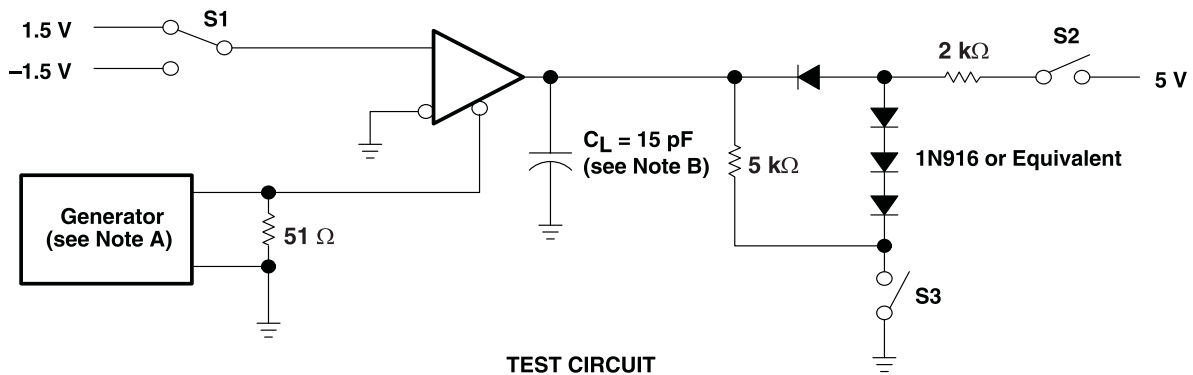


Figure 7. Receiver Propagation-Delay Times

- I. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1$ MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_o = 50 \Omega$
- J. C_L includes probe and jig capacitance.

PARAMETER MEASUREMENT INFORMATION (continued)



TEST CIRCUIT

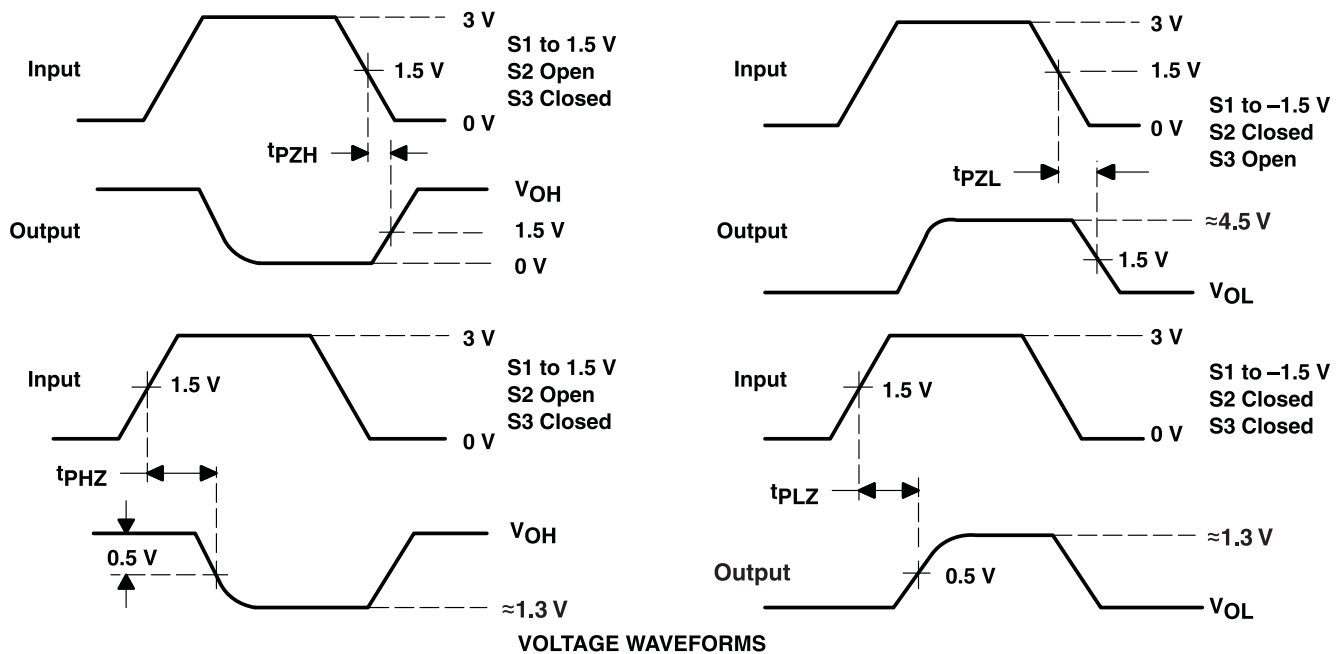


Figure 8. Receiver Output Enable and Disable Times

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75ALS181N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS181NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS181NSLE	OBSOLETE	SO	NS	14		TBD	Call TI	Call TI
SN75ALS181NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS181NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS181NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS181NSR	SO	NS	14	2000	367.0	367.0	38.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community e2e.ti.com